



Material Composition Sheet

Product: GX9533-CQYE3
 Package Type: MQFP-100pin (66/tray)
 Manufacturer: Gennum Corporation

Date: 06-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		18.67	Al	0.11	0.58	5892
			Si	18.56	99.41	994108
			Sub-total:	18.67	99.99	1000000
Die Attach	CRM 1076DS	2.80	1,4butanediolglycidylether	0.20	7.14	71429
			Ag	2.13	76.07	760714
			Epoxy Resin	0.36	12.85	128571
			Epoxy Silane	0.03	1.07	10714
			Phenol Resin	0.08	2.85	28571
			Sub-total:	2.80	99.98	999999
Lead Finish External		26.45	Sn	26.45	100.00	1000000
			Sub-total:	26.45	100.00	1000000
Lead Finish Internal		1.16	Ag	1.16	100.00	1000000
			Sub-total:	1.16	100.00	1000000
Leadframe	Olin 7025	250.70	Cu	241.17	96.19	961986
			Mg	0.38	0.15	1516
			Ni	7.52	2.99	29996
			Si	1.63	0.65	6502
			Sub-total:	250.70	99.98	1000000
Marking Ink	Teca 261	0.10		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound	EME G700	1299.71	Carbon Black	6.50	0.50	5001
			Epoxy Resin	103.98	8.00	80002
			Phenol Resin	84.48	6.49	64999
			SiO2	1104.75	84.99	849997
Sub-total:	1299.71	99.98	999999			
Wires	MGM 7	1.88	Au	1.88	100.00	1000000
			Sub-total:	1.88	100.00	1000000
Total:		1601.47				

GENNUM CORPORATION

Mailing Address: P.O. Box 489, Stn. A, Burlington, Ontario, Canada L7R 3Y3
 Shipping Address: 970 Fraser Drive, Burlington, Ontario, Canada L7L 5P5
 Tel. +1 (905) 632-2996 Fax. +1 (905) 632-5946

www.gennum.com

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